

SCSI Harbor Status



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sgi

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Status Summary

- 10x backplane prototyping completed
- Five sets of drives completed thermal testing (separate presentation)
- 15x backplane design nearing completion



Progress

- 10 device backplane received from Molex (Guadalajara)
- Working on next generation wrapper design (dock deflection, EMI gasket, Zn material issues) (separate presentation)
- Completed initial shock isolation bumper studies (separate presentation)



Backplane Status

- 10 drive backplane
 - bareboards received 10/19/99
 - PCAs received 11/4/99
- 15 drive backplane
 - received expanders from LSI Logic
 - 2 buses - 8 and 7 drives per bus
 - 15x connector (1.0 inch design)
 - LVD only
 - 110 Ohm differential impedance



Schedule

- Testing (round 1)
 - Present results Jan x, 1999
- Design
 - Design review Jan x, 1999
 - Design review Mar 2000
 - Finalize design May 2000



Issues

- Intel to provide design personnel (3/99)
- Folding SCSI Harbor into SSI Forum (separate presentation)
- January meeting date to be decided
- Intermec patent litigation
- Drive Proprietary Information
 - PES & error rejection curve information
 - Quantum, IBM, Hitachi must supply
- Dock deflection due to force from RV springs
- IP and licensing issues
- Business plan for wrappers



Drive Receipt

- Seagate - received 6 of 6 sets
- IBM - received 6 of 6 sets
- Hitachi - received 2 of 2 sets
- Fujitsu - performing testing in Japan
- Quantum - awaiting drives
- Western Digital - not participating in round 1, purchasing full set of round 2 prototypes for testing



Goals for Next Review

- Jan 2000, Location
- Hold Design Review
 - Incorporate thermal and RV results into redesign
 - Thermal results to include backplane
 - Discuss detailed feature design for wrapper, handle, EMI, and bezel
 - Attendees should include mechanical experts from drive mfgs to discuss drive specific needs